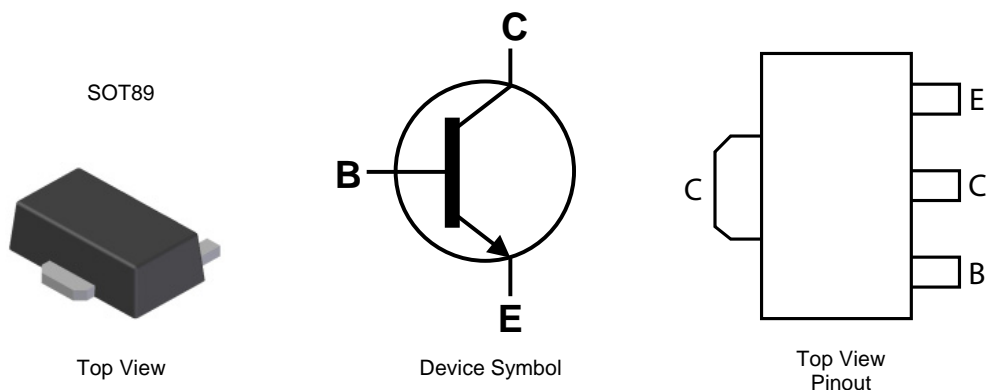


**Features**

- $BV_{CE0} > 60V$
- $I_C = 3A$  high Continuous Current
- Low saturation voltage  $V_{CE(sat)} < 300mV @ 1A$
- Complementary PNP Type: DXT751
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

**Mechanical Data**

- Case: SOT89
- Case material: Molded Plastic. "Green" Molding Compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208
- Weight: 0.052 grams (Approximate)


**Ordering Information** (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DXT651-13	KN2	13	12	2,500
DXT651-13R	KN2	13	12	4,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
  3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

**Marking Information**


KN2 = Product Type Marking Code  
 DII = Manufacturer's Marking Code  
 YWW = Date Code Marking  
 Y = Last digit of year (ex: 7 = 2007)  
 WW = Week code (01 – 53)

### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

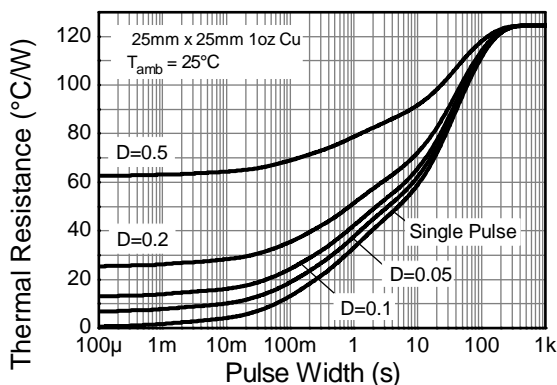
Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	80	V
Collector-Emitter Voltage	V <sub>CEO</sub>	60	V
Emitter-Base Voltage	V <sub>EBO</sub>	5	V
Collector Current	I <sub>C</sub>	3	A
Peak Pulse Collector Current	I <sub>CM</sub>	6	A
Base Current	I <sub>B</sub>	500	mA

### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

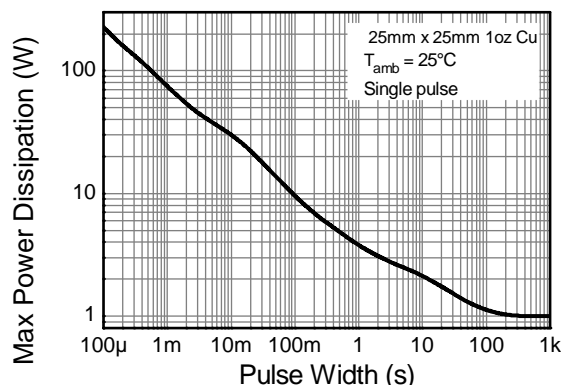
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	1	W
Thermal Resistance, Junction to Ambient Air (Note 5)	R <sub>θJA</sub>	125	°C/W
Thermal Resistance, Junction to Leads (Note 6)	R <sub>θJL</sub>	18.2	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

- Notes:
5. For a device surface mounted on 25mm X 25mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
  6. Thermal resistance from junction to solder-point (on the exposed collector pad).

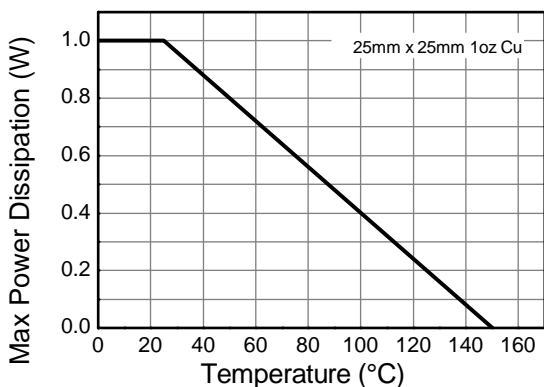
### Thermal Characteristics and Derating Information



**Transient Thermal Impedance**



**Pulse Power Dissipation**



**Derating Curve**

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
<b>OFF CHARACTERISTICS (Note 7)</b>						
Collector-Base Breakdown Voltage	$BV_{CBO}$	80	—	—	V	$I_C = 100\mu\text{A}$ , $I_E = 0$
Collector-Emitter Breakdown Voltage	$BV_{CEO}$	60	—	—	V	$I_C = 10\text{mA}$ , $I_B = 0$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	5	—	—	V	$I_E = 100\mu\text{A}$ , $I_C = 0$
Collector-Base Cutoff Current	$I_{CBO}$	—	—	0.1 10	$\mu\text{A}$	$V_{CB} = 60\text{V}$ , $I_E = 0$ $V_{CB} = 60\text{V}$ , $I_E = 0$ , $T_A = +100^\circ\text{C}$
Emitter-Base Cutoff Current	$I_{EBO}$	—	—	0.1	$\mu\text{A}$	$V_{EB} = 4\text{V}$ , $I_C = 0$
<b>ON CHARACTERISTICS (Note 7)</b>						
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	—	0.08 0.23	0.3 0.6	V	$I_C = 1\text{A}$ , $I_B = 100\text{mA}$ $I_C = 3\text{A}$ , $I_B = 300\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(sat)}$	—	0.85	1.25	V	$I_C = 1\text{A}$ , $I_B = 100\text{mA}$
Base-Emitter Turn-On Voltage	$V_{BE(on)}$	—	0.8	1	V	$V_{CE} = 2\text{V}$ , $I_C = 1\text{A}$
DC Current Gain	$h_{FE}$	70 100 80 40	200 200 185 120	— 300 — —	—	$V_{CE} = 2\text{V}$ , $I_C = 50\text{mA}$ $V_{CE} = 2\text{V}$ , $I_C = 500\text{mA}$ $V_{CE} = 2\text{V}$ , $I_C = 1\text{A}$ $V_{CE} = 2\text{V}$ , $I_C = 2\text{A}$
<b>AC CHARACTERISTICS</b>						
Transition Frequency	$f_T$	140	200	—	MHz	$V_{CE} = 5\text{V}$ , $I_C = 100\text{mA}$ , $f = 100\text{MHz}$
Output Capacitance	$C_{obo}$	—	—	30	pF	$V_{CB} = 10\text{V}$ , $f = 1\text{MHz}$
Switching Times	$t_{on}$ $t_{off}$	— —	35 230	— —	ns ns	$V_{CC} = 10\text{V}$ , $I_C = 500\text{mA}$ , $I_{B1} = I_{B2} = 50\text{mA}$

Notes: 7. Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ . Duty cycle  $\leq 2\%$ .

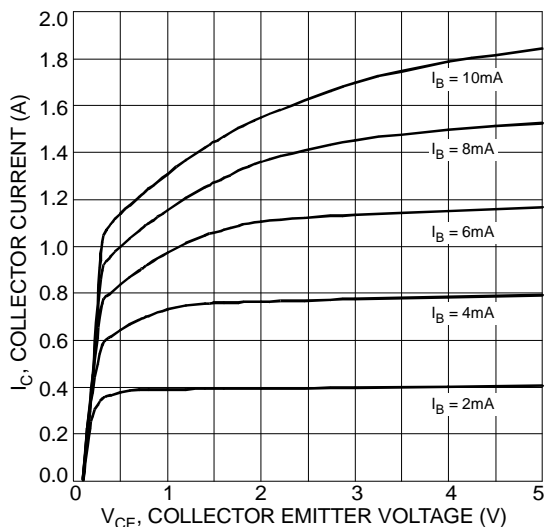


Fig. 2 Typical Collector Current vs. Collector-Emitter Voltage

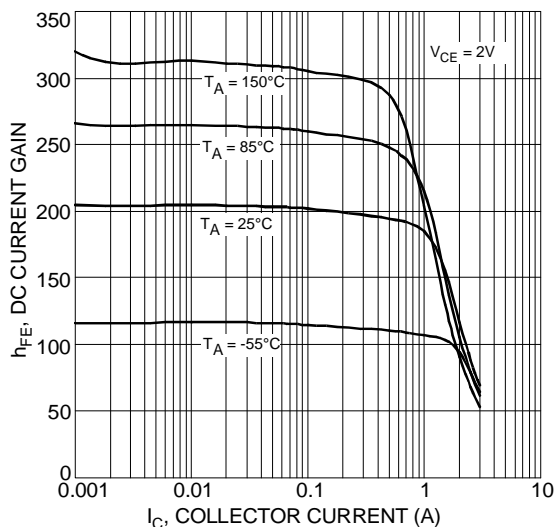


Fig. 3 Typical DC Current Gain vs. Collector Current

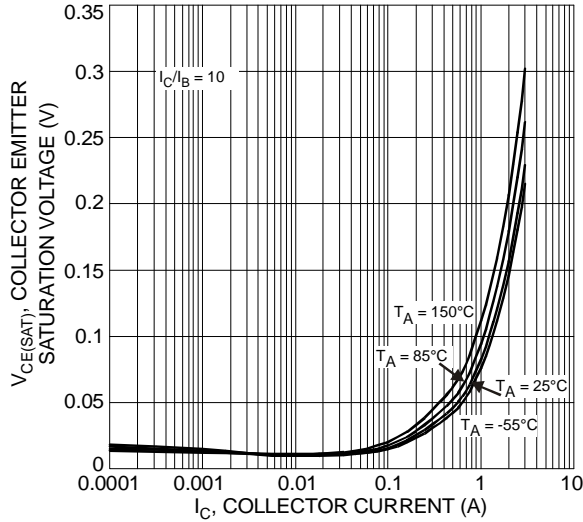


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

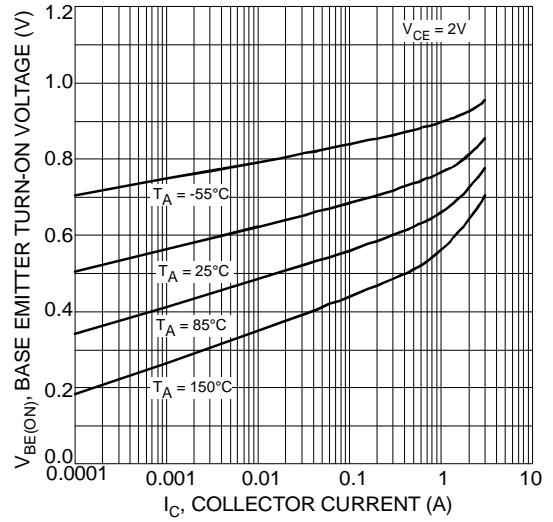


Fig. 5 Typical Base-Emitter Turn-On Voltage vs. Collector Current

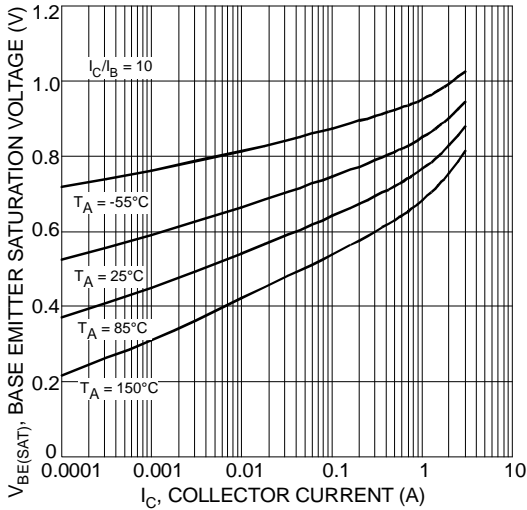


Fig. 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

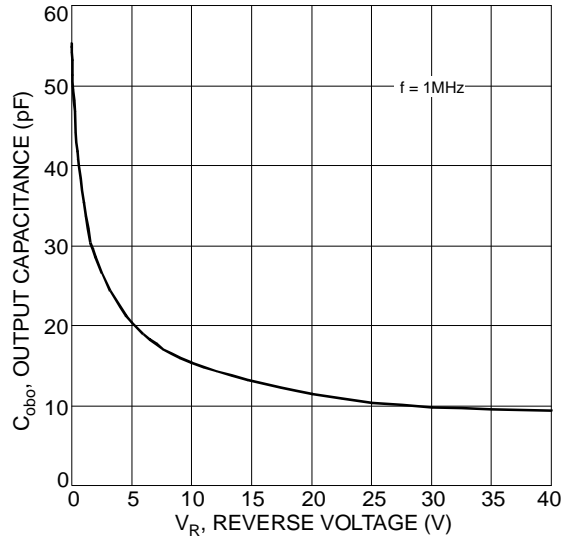


Fig. 7 Typical Output Capacitance Characteristics

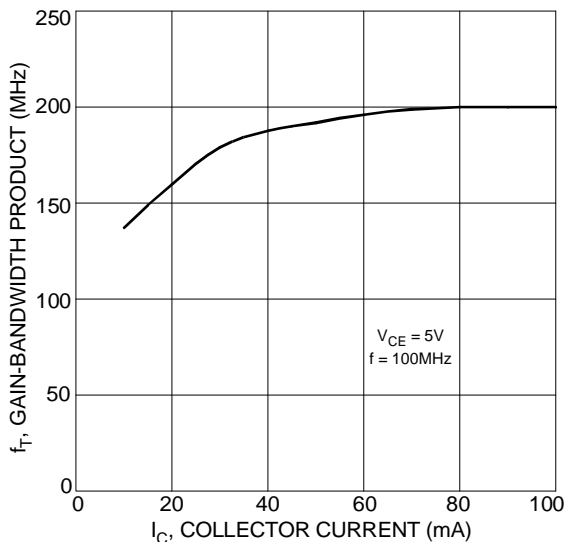
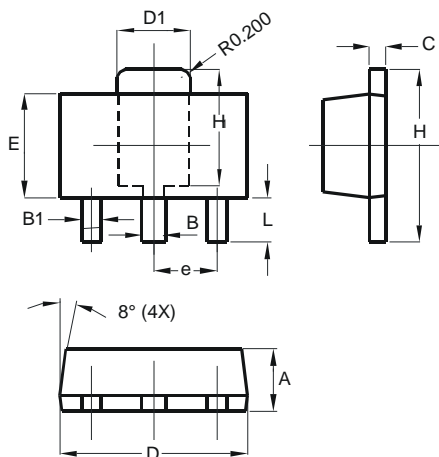


Fig. 8 Typical Gain-Bandwidth Product vs. Collector Current

## Package Outline Dimensions

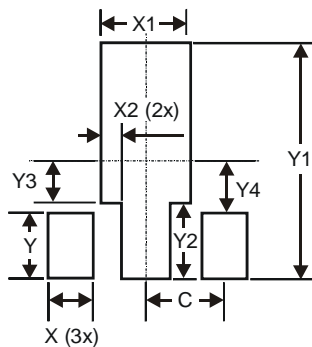
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT89		
Dim	Min	Max
A	1.40	1.60
B	0.44	0.62
B1	0.35	0.54
C	0.35	0.44
D	4.40	4.60
D1	1.62	1.83
E	2.29	2.60
e	1.50 Typ	
H	3.94	4.25
H1	2.63	2.93
L	0.89	1.20
All Dimensions in mm		

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
C	1.500

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